IN THE CLAIMS

1. (Original) A system for cooling a semiconductor die, comprising:

a die having plurality of micro-channels; and

a condenser in fluid communication with the micro-channels, wherein die heating vaporizes fluid at the die to force fluid towards the condenser.

2. (Original) A system of claim 1, further comprising a plate coupled with the die for sealing the micro-channels such that the micro-channels form a plurality of fluid conduits for the fluid.

3. (Original) A system of claim 2, the plate being formed of semiconductor material.

4. (Original) A system of claim 3, the plate being selected from the group consisting of glass and silicon.

5. (Original) A system of claim 1, further comprising fluid selected from the group consisting of water, Fluorinert and alcohol.

6. (Original) A system of claim 1, further comprising a first fluid conduit for coupling cooler fluid from the condenser to the micro-channels.

7. (Original) A system of claim 6, further comprising a first header for coupling the first fluid conduit to the micro-channels.

8. (Currently Amended) A system of claim ~~1~~7, further comprising a second fluid conduit for coupling warmer fluid from the micro-channels to the condenser.

9. (Original) A system of claim 8, further comprising a second header for coupling the second fluid conduit to the micro-channels.

10. (Original) A system of claim 1, the micro-channels being shaped for preferential fluid flow along one direction in the micro-channels.

11. (Original) A system of claim 1, the condenser being constructed and arranged above the die wherein gravity pressurizes cooler condenser fluid towards the die.

12. (Original) A system of claim 1, further comprising at least one orifice for restricting fluid flow through at least one of the micro-channels, for preferential fluid flow along one direction in the micro-channels.

13. (Original) A system of claim 1, the condenser comprising one or more fins for enhancing heat transfer to air adjacent the condenser.